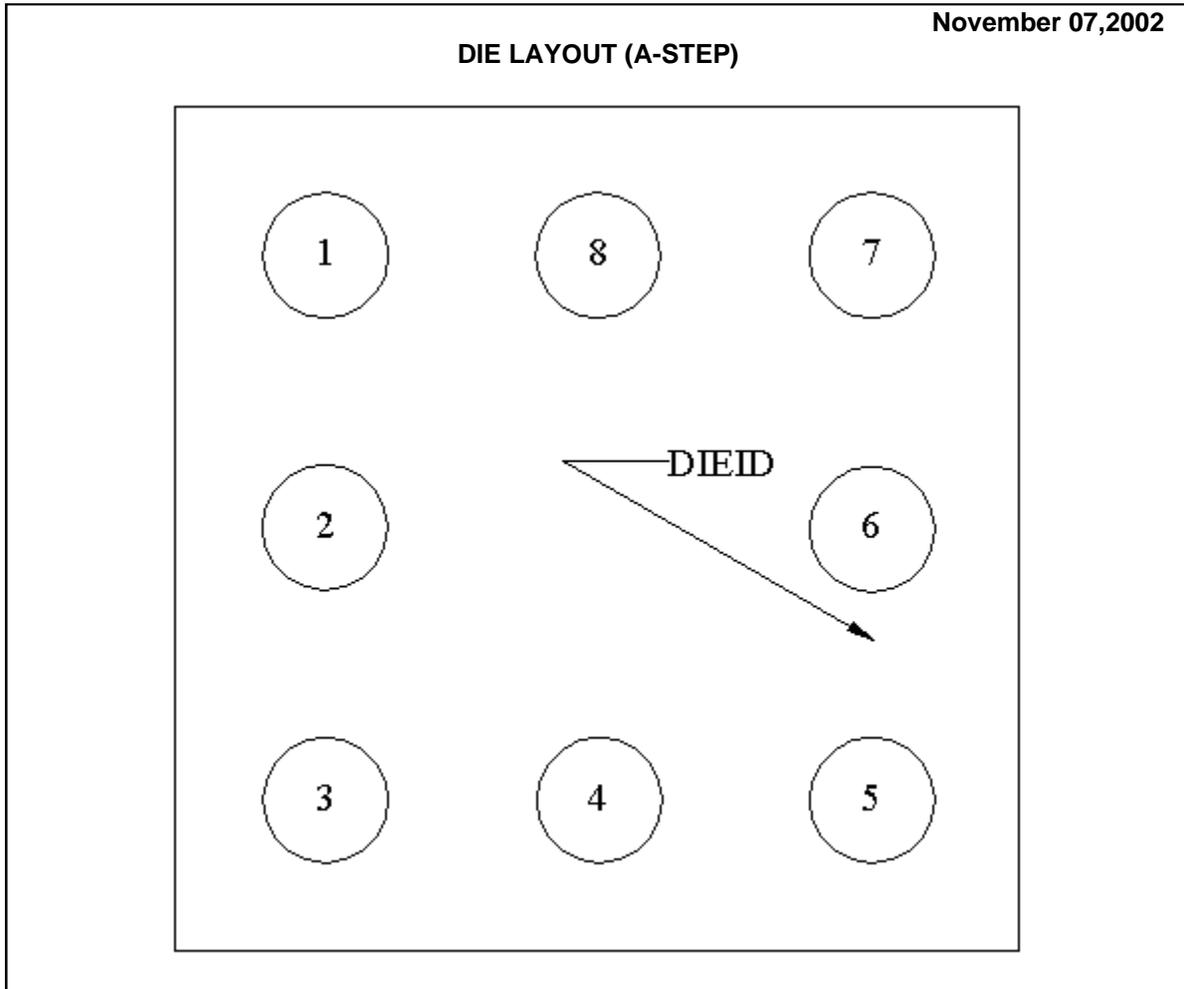


**LMV243 MDA**  
**SINGLE-CHANNEL, QUAD-BAND GSM POWER CONTROLLER**



**DIE/WAFER CHARACTERISTICS**

<b>Fabrication Attributes</b>		<b>General Die Information</b>	
Physical Die Identification	LMV243A	Bond Pad Opening Size (min)	230µm x 230µm
Die Step	A	Bond Pad Metalization	0.5% COPPER_BAL. ALUMINUM
<b>Physical Attributes</b>		Passivation	VOM NITRIDE
Wafer Diameter	200mm	Back Side Metal	UNGROUND
Die Size (Drawn)	1549µm x 1549µm 61mils x 61mils	Back Side Connection	Floating
Thickness	216µm Nominal		
Min Pitch	500µm Nominal		

**Special Assembly Requirements:**

**Note: Actual die size is rounded to the nearest micron.**

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Die Bond Pad Coordinate Locations (A -Step)						
(Referenced to die center, coordinates in $\mu\text{m}$ ) <b>NC</b> = No Connection						
SIGNAL NAME	PAD# NUMBER	X/Y CORRDINATES		PAD SIZE		
		X	Y	X	Y	
V <sub>DD</sub>	1	-500	500	230	x	230
RF IN	2	-500	0	230	x	230
GND	3	-500	-500	230	x	230
TX_EN	4	0	-500	230	x	230
V <sub>RAMP</sub>	5	500	-500	230	x	230
OUT	6	500	0	230	x	230
COMP	7	500	500	230	x	230
GND	8	0	500	230	x	230

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**IN U.S.A.**

Tel: 1 877 Dial Die (1 877 342 5343)  
Fax: 1 207 541 6140

**IN EUROPE**

Tel: 49 (0) 8141 351492 / 1495  
Fax: 49 (0) 8141 351470

**IN ASIA PACIFIC**

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